

Global 3D IC and 2.5D IC Packaging Market Research Report 2017

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Abstracts

In this report, the global 3D IC and 2.5D IC Packaging market is valued at USD XX million in 2016 and is expected to reach USD XX million by the end of 2022, growing at a CAGR of XX% between 2016 and 2022.

Geographically, this report is segmented into several key Regions, with production, consumption, revenue (million USD), market share and growth rate of 3D IC and 2.5D IC Packaging in these regions, from 2012 to 2022 (forecast), covering

United States

EU

China

Japan

South Korea

Taiwan

Global 3D IC and 2.5D IC Packaging market competition by top manufacturers, with production, price, revenue (value) and market share for each manufacturer; the top players including

Taiwan Semiconductor

Samsung Electronics

Toshiba Corp

Advanced Semiconductor Engineering

Amkor Technology

On the basis of product, this report displays the production, revenue, price, market share and growth rate of each type, primarily split into

3D wafer-level chip-scale packaging

3D TSV

2.5D

On the basis of the end users/applications, this report focuses on the status and outlook for major applications/end users, consumption (sales), market share and growth rate for each application, including

Logic

Imaging & optoelectronics

Memory

MEMS/sensors

LED

Power

If you have any special requirements, please let us know and we will offer you the report as you want.

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